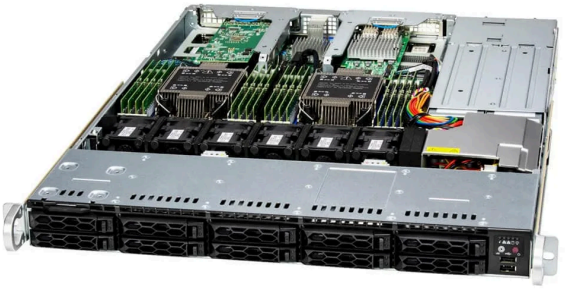
Intel Xeon (X13) | 1U Rackmount | Server

Supermicro SYS-121C-TN10R

Intel Xeon (X13) · 1U Rackmount Server

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Form Factor	CPU
1U Rackmount	**5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors**
GPU	**Memory**
Up to 2 single-width GPUs	**Max Memory (1DPC): Up to 4TB 5600MT/s ECC DDR5 RDIMM**

Key Features

- Dual sockets E (LGA-4677) 5th and 4th Gen Intel® Xeon® Scalable processors
- 16 DIMMs up to 4TB 3DS ECC DDR5-5600: RDIMM
- 2 PCIe 5.0 x16 FHHL; 2 PCIe 5.0 x4 NVMe M.2
- Dual AIOM (OCP 3.0) slots with NCSI for networking, 1 dedicated IPMI LAN
- 10x 2.5" hot-swap hybrid NVMe/SATA/SAS drive bays
- 6 counter-rotating 4 cm PWM fans with optimal fan speed control, 2 air shrouds
- 860W redundant Titanium level 100-240Vac and 200-240 Vdc power supplies
- 1 VGA, 1 COM, 2 USB 3.0 (rear), 2 USB 2.0 (front)

Form Factor	1U Rackmount
Platform	Intel Xeon (X13)
CPU	Dual Socket E (LGA-4677) 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors
Max GPU Count	Up to 2 single-width GPUs
Supported GPU	NVIDIA PCIe: A2, L4
Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 5600MT/s ECC DDR5 RDIMM
Drive Bays	Default: Total 10 bays10 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays
Fans	Up to 6x 4cm heavy duty fans with optimal fan speed control

Power Supply	2x 860W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Full Specifications — SYS-121C-TN10R

Product SKUs

Part numbers	SYS-121C-TN10R

Motherboard

Motherboard	Super X13DDW-A

Processor

CPU	Dual Socket E (LGA-4677) 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors
Core Count	Up to 36C/72T; Up to 82.5MB Cache per CPU
Note	Supports up to 270W TDP CPUs (Air Cooled)* *Air Cooled CPUs with TDP over 250W only supported under specific conditions. Contact a Supermicro representative for details.

GPU

Max GPU Count	Up to 2 single-width GPUs
Supported GPU	NVIDIA PCIe: A2, L4 Intel PCIe: Intel Data Center GPU Flex 140 View GPU Options

System Memory

Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 5600MT/s ECC DDR5 RDIMM View Memory Options
Memory Voltage	1.1V

On-Board Devices

SATA	SATA (6Gbps) ; RAID 0/1/5/10 support
NVMe	NVMe; RAID 0/1/5/10 support(VROC HW key required) View NVMe Options
Network Connectivity	Via AIOM View AIOM Options View AOC Options

Input / Output

LAN	1 RJ45 1 GbE Dedicated BMC LAN port
USB	2 USB 3.2 Gen1 Type-A ports (rear) 2 USB 2.0 Type-A ports (front)

Video	1 VGA port
Serial	1 COM port (Rear)
TPM	1 TPM header

System BIOS

BIOS Type	AMI 32MB SPI FLASH ROM

Management

Software	SuperCloud Composer® (SCC) Supermicro Server Manager (SSM) Supermicro Update Manager (SUM) Supermicro SuperDoctor® 5 (SD5) Super Diagnostics Offline (SDO) Supermicro Thin-Agent Service (TAS) SuperServer Automation Assistant (SAA) New!
Power configurations	ACPI/APM Power Management

Security

Hardware	Trusted Platform Module (TPM) 2.0 Silicon Root of Trust (RoT) – NIST 800-193 Compliant
Features	Cryptographically Signed Firmware Secure Boot Secure Firmware Updates Automatic Firmware Recovery Supply Chain Security: Remote Attestation Runtime BMC Protections System Lockdown

PC Health Monitoring

CPU	8 Phase-switching voltage regulator Monitors for CPU Cores, Chipset Voltages, Memory.
Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors

Certifications

Operating Systems	ESXi 7.0 U3, ESXi 8.0, Hypervisor 8.2.1, Oracle Linux 8.10, Oracle Linux 9.0, RHEL 8.7, RHEL 9.0, SAP HANA 2.0, SLES 12 SP5, SLES 15 SP4, Windows Server 2022, Windows Server 2025 View all OS Compatibility and Certification Matrix

Enterprise Solutions	SAP HANA

Chassis

Form Factor	1U Rackmount
Model	CSE-LB16TS-R0AWNP3

Dimensions and Weight

Height	1.7" (43 mm)
Width	17.2" (437 mm)
Depth	23.5" (597 mm)
Package	7.8" (H) x 23.8" (W) x 32.4" (D)
Weight	Gross Weight: 40 lbs (18.1 kg) Net Weight: 25 lbs (11.3 kg)
Available Color	Black front & silver body

Front Panel

Buttons	Power On/Off Unit Identifier (UID)
LED	Drive activity Network activity Power status Universal Information

Expansion Slots

PCI-Express (PCIe) Configuration	Default2 PCIe 5.0 x16 FHHL slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) 2 PCIe 5.0 x16 FHHL slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) View AOC Options

Drive Bays / Storage

Drive Bays Configuration	Default: Total 10 bays10 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays 10 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays (*NVMe/SAS/SATA support may require additional storage controller and/or cables, please see the optional parts list for details) View NVMe Options View Drive Options
M.2	2 M.2 PCIe 5.0 x4 NVMe slots (M-key 2280; VROC required for RAID) View M.2 Options

System Cooling

Fans	Up to 6x 4cm heavy duty fans with optimal fan speed control
Air Shroud	2 Air Shrouds

Power Supply

2x 860W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Dimension (WxHxL)	54.5 x 40.25 x 322 mm
Input	800W: 100-127Vac / 50-60Hz 860W: 200-240Vac / 50-60Hz 860W: 240Vdc / 50-60Hz
+12V	Max: 66.67A / Min: 0A (100Vac-127Vac) Max: 71.67A / Min: 0A (Vdc-240Vdc) Max: 71.67A / Min: 0A (200Vac-240Vac)
5V SB	Max: 4A / Min: 0A
Output Type	Backplanes (gold finger)

Operating Environment

RoHS	RoHS Compliant
Environmental Spec.	Name: A2 Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 80% (max 21° DP; non-condensing) Non-operating Relative Humidity: 8% to 90% (max 38° DP; non-condensing)